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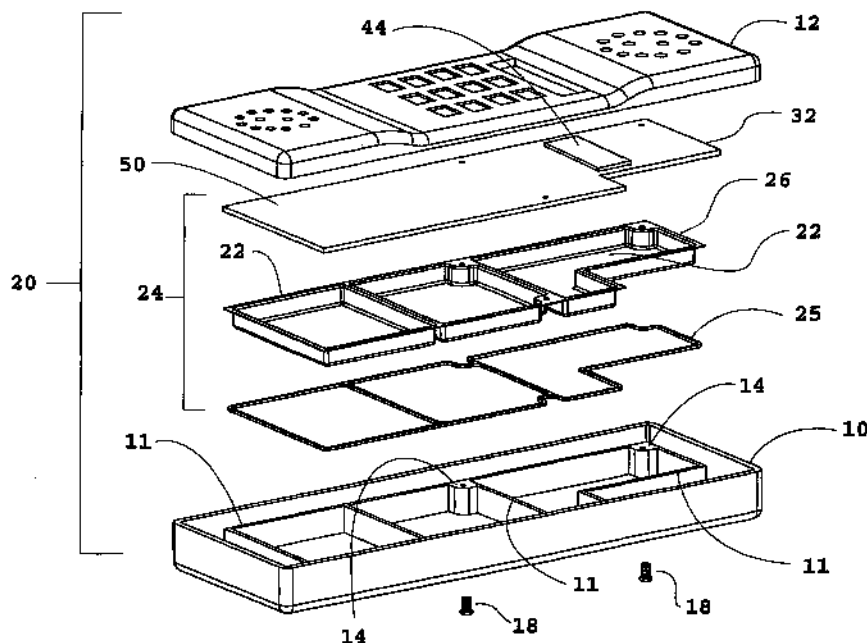
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(54) Title: EMI AND RFI CONTAINMENT ENCLOSURE FOR ELECTRONIC DEVICES



(57) Abstract: An EMI shield system for containing EMI emissions in electronic devices includes a thermo-formable shield component (26) maintained in contact with a ground trace (46) on a printed-circuit board (32). A rib system (11) integral with an injection-molded housing component (10) forces the thermo-formed shield component against the ground trace (46). An elastomeric gasket (25) between the rib system (11) and the thermo-formed component insures a firm, compliant seal against the ground trace.



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